

PM-3100

Modular Fanless Box PC with 8th/9th Gen Intel® Core™ i Processor (LGA1151)



Applications

- Factory Automation
- Self-Service Kiosk
- Human Machine Interface(HMI)
- Warehouse Management
- iHealthcare

Features

- Intel® 8th/9th Gen Core™ i3/i5/i7 Processor (LGA1151) with Q370 chipset
- 2 x DDR4-2666 SO-DIMM, Dual Channel, Max to 64GB
- Supports 1 x DP, 1 x VGA, 1 x DVI-D
- 2 x Intel® i210-AT, 1 x Intel® i219-LM Gigabit Ethernet port
- 4 x Mini-PCIe expansion slots
- 9~48V DC Input with Power Ignition Function
- -40°C to 70°C Operating Temperature
- Built-in Power Protection (OVP/OCP/RVP)

Ordering Information

Part No.	Description
PM-3100	Fanless Box PC with Intel® 8 th /9 th Gen Core™ i LGA1151 Processor, 6 x USB3.2 Gen 2, 2 x USB2.0, 6 x RS232/422/485, 3 x GbE, 1x DP, 1 x VGA, 1 x DVI-D, Line Out, Mic In, DC 9~48V, Terminal Block Connector

Packing List

Description
1 x PM-3100

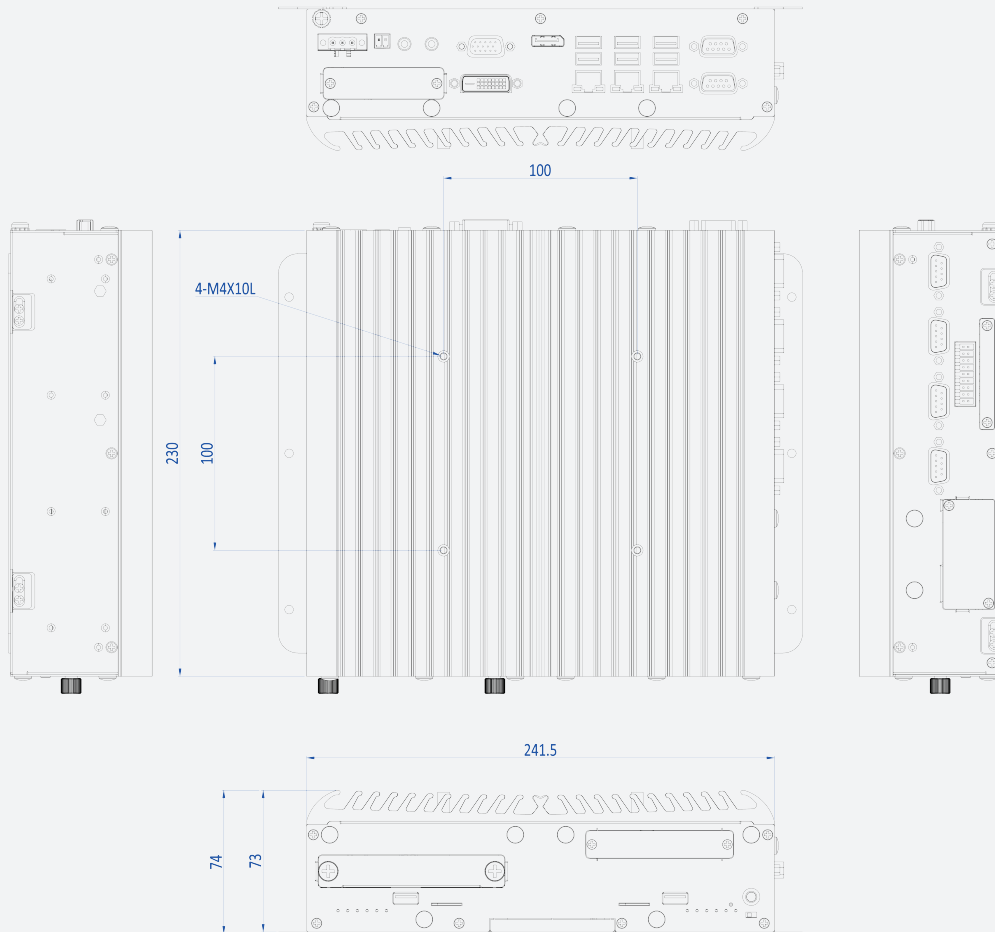
Optional Items

Part No.	Description
AWD-4G003	4G(LTE) EG25-G + 2 Antennas, Full Size (For Global)
AWD-WF001	Wi-Fi 802.11 bgn (1T1R) + 1 Antenna (Single Band), Half-size miniPCIe
AWD-WF003	Wi-Fi 802.11 a/b/g/n/ac/BT4.0 (2T2R) + 2 Antennas (Dual Band), Half-size mini PCIe
i7-9700TE	Intel® Core™ i7-9700TE (8-core, up to 3.8 GHz, 35W TDP)
i5-9500TE	Intel® Core™ i5-9500TE (6-core, up to 3.6 GHz, 35W TDP)
i7-8700T	Intel® Core™ i7-8700T (6-core, up to 4.0 GHz, 35W TDP)
i5-8500T	Intel® Core™ i5-8500T (6-core, up to 3.5 GHz, 35W TDP)
i3-8100T	Intel® Core™ i3-8100T (4-core, up to 3.1 GHz, 35W TDP)
External Fan	External Fan Module Kit (92 x 92 x 25 mm) (for 65W CPU Option)
55000-0023-M5	Adapter AC/DC 24V 5A 120W, 3-pin Terminal Block Plug 5.0mm Pitch
55000-0024-M5	Adapter AC/DC 24V 9.2A 220W, 3-pin Terminal Block Plug 5.0mm Pitch
30100-0003-CA	Power Cord, 3-pin US Type, 180cm
30101-0005-CA	Power Cord, 3-pin EU Type, 180cm

Specifications

Model		PM-3100
Processor System	CPU	8 th /9 th Intel® Core™ i3 / i5 / i7 Desktop 35W LGA 1151 Processors
	Frequency	up to 4.00GHz
	System Chipset	Intel® Q370
	BIOS	AMI BIOS, 64Mbit SPI Flash ROM built on board
Memory	Technology	2 x DDR4-2666MHz 260-Pin SO-DIMM Socket
	Max. Capacity	Supports up to 64GB (Unbuffered and Non-ECC)
Display	DP	1 x DP (4096x2160)
	VGA	1 x VGA (1920x1200)
	DVI	1 x DVI-D (1920x1200)
I/O Interface	USB	6 x USB3.2 and 2 x USB2.0
	Serial Port	6 x RS232/422/485 with Auto Flow Control, DB9
	GPIO	8 x Isolated DI and 8x Isolated DO Port, 2x9-pin Terminal Block
	Ethernet	3 x GbE (1 x Intel® i219-LM, 2 x Intel® i210-AT GbE, Supporting Wake-on-LAN and PXE)
	Audio	Line Out, Mic In
	CMOS Battery	1 x Removable CMOS Battery
	Antenna Hole	10
	Flexible I/O Window Slot	1
	Others	1 x Power On/Off Button 1 x External Power On/Off Connector, 2-pin Terminal Block 1 x AT/ATX Mode Switch and 1 x PC/Car Mode Switch 1 x Clear CMOS Switch and 1 x Removable CMOS Battery
Expansion	Mini-PCle	2 x Full-size Mini-PCle Sockets (Mux with mSATA) 2 x Full-size Mini-PCle Sockets
	SIM Holder	4
Storage	2.5" SATA HDD Bay	1 x Removable 2.5" SATA HDD Bay and 1 x Internal 2.5" SATA HDD Bay
	mSATA	2 x mSATA Sockets (Mux with 2 x Mini-PCle and 2 x CFast)
	CFast	2 x CFast Sockets (Shared by 2 x mSATA)
Power	Power Mode	Support Hardware AT, ATX Power Mode
	Power Supply Voltage	9~48V DC Input
	Connector Type	1 x 3-pin Terminal Block Connector
	Power Ignition	Power Ignition Sensing
	Protection	Over Voltage Protection (OVP) up to 52V
		Reverse Voltage Protection (RVP) up to -48V
		Over Current Protection (OCP) 20A
	Power Adapter	1 x Optional AC/DC 24V/5A, 120W Power Adapter or 1 x Optional AC/DC 24V 9.25A, 220W Power Adapter
Mounting	Type	VESA Mounting (100 x 100mm)
Environment	Operating Temperature	-40~70° C
	Storage Temperature	-40~80° C
	Humidity	10%~80%, Non-condensing
	Vibration	5Grms, 5-500Hz, 3Axis
	Shock	50Grms, Half-sine 11ms
	Certification	CE/FCC
	Thermal Dissipation	Fanless System
	Material	Extruded Aluminum with Heavy Duty Metal
General	Dimensions (W x H x D)	241.5 x 73 x 230mm
	Net Weight	3.3kg
	Operating System	Windows 11 (IoT/ Professional), Windows 10 IoT, Linux

Dimensions



Viewing

